

Docket No.: 27-035.D1

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**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of:	John Briar	:	Confirmation No.:
Serial No.:	Not yet assigned	:	Art Unit: 2811
Filed:	October 24, 2003	:	Examiner: Douglas W. Owens
For:	FLIP CHIP MOLDED/EXPOSED DIE PROCESS AND PACKAGE STRUCTURE	:	

Mail Stop Patent Application  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**PRELIMINARY AMENDMENT**

Sir:

The following Preliminary Amendment and Remarks are submitted concurrently with the filing of a Divisional patent application, identified by attorney docket no. 27-035.D1, following the procedures set forth in 37 CFR §1.121.

After this introductory section, there are Amendments to the Specification, Amendments to the Claims, Amendments to the Drawings, and then Remarks, each starting on a separate page.

Amendments to the Specification consist of modifications, which conform this application with amendments made to the allowed parent application. Drawing amendments consist of adding a reference number for FIG. 4b. Amendments to the Claims consist of the cancellation of claims 1-11 and 22 and amendments for claims 12, 14, and 16 - 21, which are incorporated in a complete listing of the claims.